

Layer Stack Up Detail for: TIDA-00498.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-408
Bottom Layer	(.GBL)	1.4mil	FR-408
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
5118.11MIL X 2283.47MIL

Number of Layers : 2
 MIN. TRACK WIDTH: 6 MIL
 MIN. CLEARANCE: 8 MIL
 MIN. VIA PAD SIZE: 19.685MIL

MINIMUM ANNULAR RING 0.15 (5.9055MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 63 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

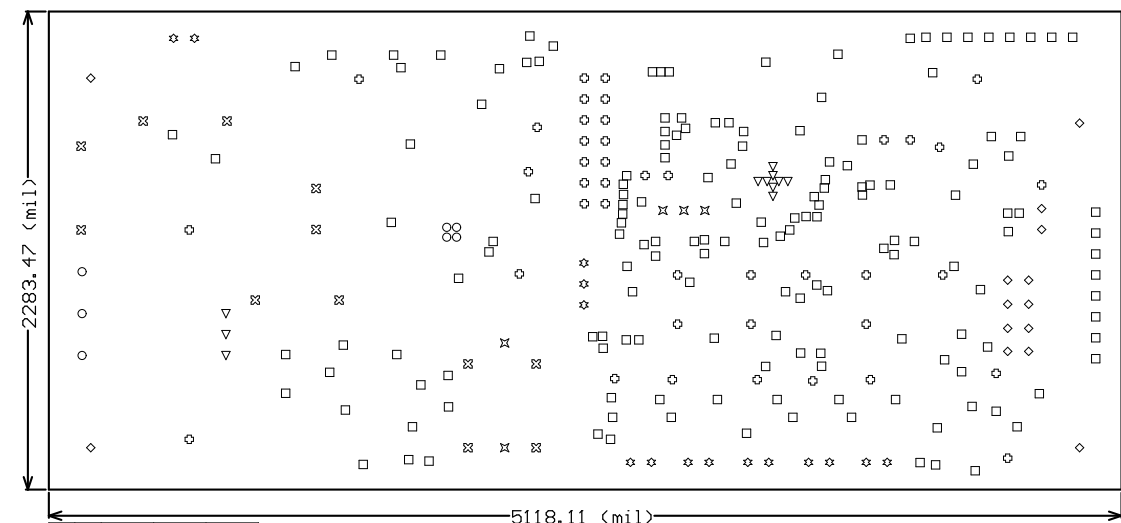
BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENTING: YES NO
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAIL METAL SILK



Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	8	7.874mil (0.2mm)	PTH	Round
□	146	12mil (0.305mm)	PTH	Round
○	4	12.992mil (0.33mm)	PTH	Round
⊗	3	31.496mil (0.8mm)	PTH	Round
⊙	3	33.465mil (0.85mm)	PTH	Round
⊗	2	36mil (0.914mm)	PTH	Round
⊙	10	38mil (0.965mm)	PTH	Round
⊕	40	40mil (1.016mm)	PTH	Round
□	16	43.307mil (1.1mm)	PTH	Round
⊗	12	44mil (1.118mm)	PTH	Round
⊙	10	45.276mil (1.15mm)	PTH	Round
▽	3	50mil (1.27mm)	PTH	Round
⊗	2	51mil (1.295mm)	PTH	Round
○	3	52mil (1.321mm)	PTH	Round
⊕	2	106.5mil (2.705mm)	PTH	Round
⊙	4	125.984mil (3.2mm)	PTH	Round
268 Total				

Drill Table

DRILL TOLERANCES:
 FOR PTH +/-3MILS
 7.874mil drill:+0/-7.874mil
 12mil drill:+0/-12mil
 12.992mil drill:+0/-12.992mil

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00498	REV: E2	Not In VersionControl
LAYER NAME = MiBoardOutline	MCCB/ACB FE_TU		
PLOT NAME = Fabrication Drawing	GENERATED : 6/2/2015 3:04:18 PM	TEXAS INSTRUMENTS	

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TEXAS INSTRUMENTS

PROJECT TITLE:
MCCB/ACB FE_TU

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-00498.PcbDoc

ENGINEER:
Sreenivasa

LAYOUT BY:
Manjunath M

SCALE: 1.00

ALTIM DESIGNER VERSION:
10.0.0.27009

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